

OXE800DSE Network Attached Storage Device

Features

- Flexible, extendable storage
 - Seamless interface to 2 internal SATA drives, expandable via PCI SATA bridge chips
- Accessible from multiple clients using Ethernet (integrated 10/100 Ethernet MAC) or 802.11 WiFi (via PCI WiFi chips)
- 200-MHz ARM926EJ-S processor with 32-Kbyte caches & MMU
- Network coprocessor
 - TCP / IP acceleration
- Supports multiple software architectures
 - Linux OS
 - TCP/IP & CIFS
 - EXT3
- Simple to install—no specialist user knowledge necessary; automatic installation with DHCP client & simple configuration
- RAID 1 hardware accelerator
- Integrated fan/tacho/PWM
- AES-based encryption supports multiple authentication methods & devices for secure storage of user data
- 5-channel DMA controller
- USB 2.0 & USB full-speed host controllers
- 32-Kbyte on-chip SRAM
- DDR SDRAM controller with selectable 8 & 16-bit interface supports combinations up to 64 Mbytes addressable storage
- 16-bit static memory interface (optional—device boots from HDD) supports up to 4 Mbytes addressable storage per chip-select
- 0.13- μ m CMOS process with 1.2-V core
- 19 mm \times 19 mm 272-pin PBGA (1-mm ball pitch)

Overview

The OXE800DSE delivers a powerful network storage product combined with software that prioritizes ease of use. These primary characteristics make it ideal for customers without specialized IT knowledge and especially useful in the small office or the home, where the RAID and encryption facilities of the OXE800DSE are particularly suitable for storing critical data such as sensitive information and digital photos.

The OXE800DSE combines a wealth of potential with low cost of ownership. It delivers a high level of integration and its minimal requirements for external components render it particularly suitable for the following application areas:

- Networked consumer PC cluster
- Small office/home office
- Consumer media storage or server device

Functionality

The Oxford Semiconductor OXE800DSE is a network-attached storage (NAS) device with advanced encryption capabilities which allow it to store data securely. It offers diverse connectivity including 10/100 Ethernet plus CIFS over TCP/IP, and EXT3 with optional RAID capabilities.

This adaptable and highly-configurable device also supports connections to 802.11 and other standard wireless chips via mini PCI. It provides two integrated SATA cores (expandable via a PCI bus), a USB high-speed port and two USB full-speed host ports with print server function, and additional expansion capability via USB HDDs. The RAID controller provides a high-level control interface with a common data path from the enhanced DMA engine to either or both SATA blocks. It supports RAID1, disk spanning or two independent disk configurations, and also a port multiplier for expanded configurations on either port.

An integrated ARM926EJ-S processor, featuring an MMU and 32-Kbyte caches, runs Linux OS with a full network stack. For off-chip control, the integrated fan/tachometer/pulse width modulator provides counter functionality and a thermistor circuit. Used in conjunction, these facilities can optionally trigger and modulate a fan or initiate protective measures. Alternatively, the core can be used to provide low-resolution analogue output controls for any other function.

Figure 1 shows the OXE800DSE.

Figure 1 OXE800DSE

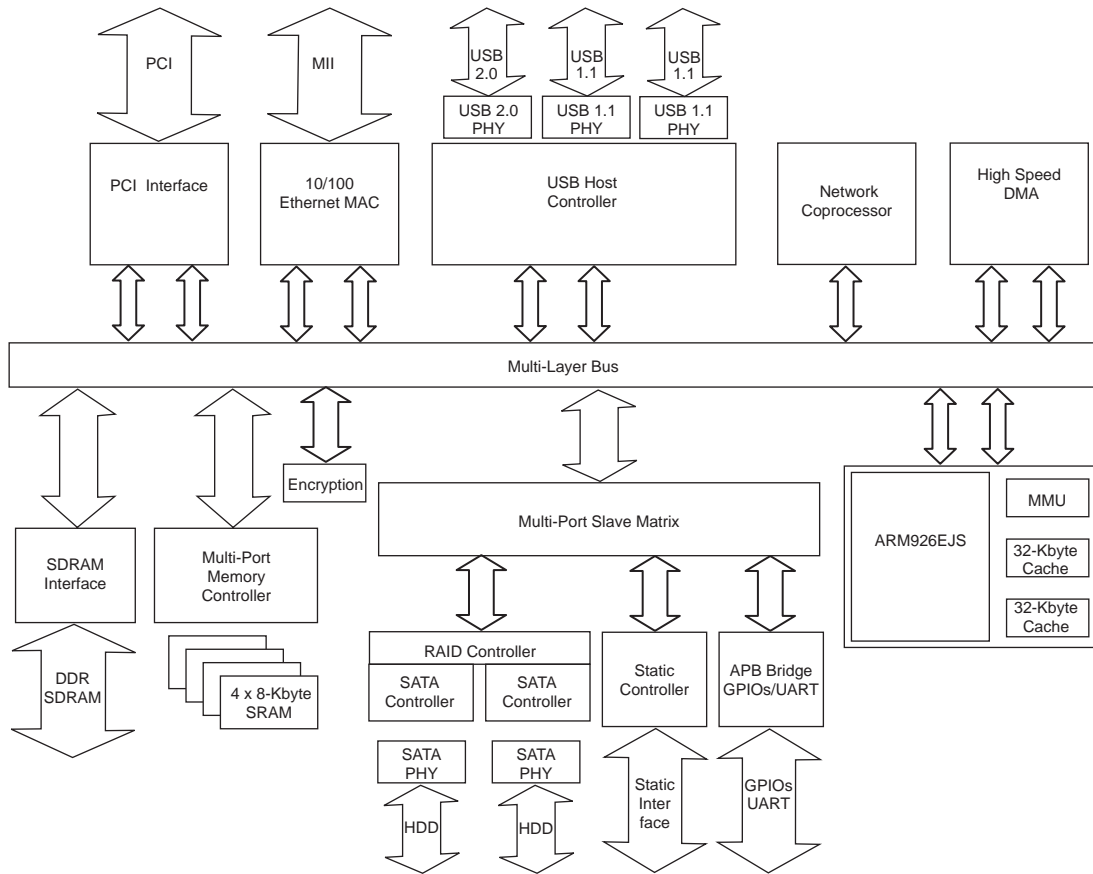


Figure 2 shows a sample low-cost application in which the OXE800DSE uses a single 25-MHz crystal and can boot directly from disk without the need for flash memory.

Figure 2 Sample OXE800DSE Boot-From-HDD Application

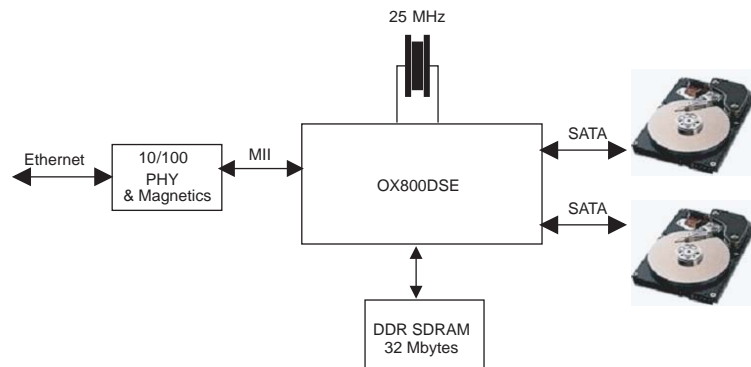
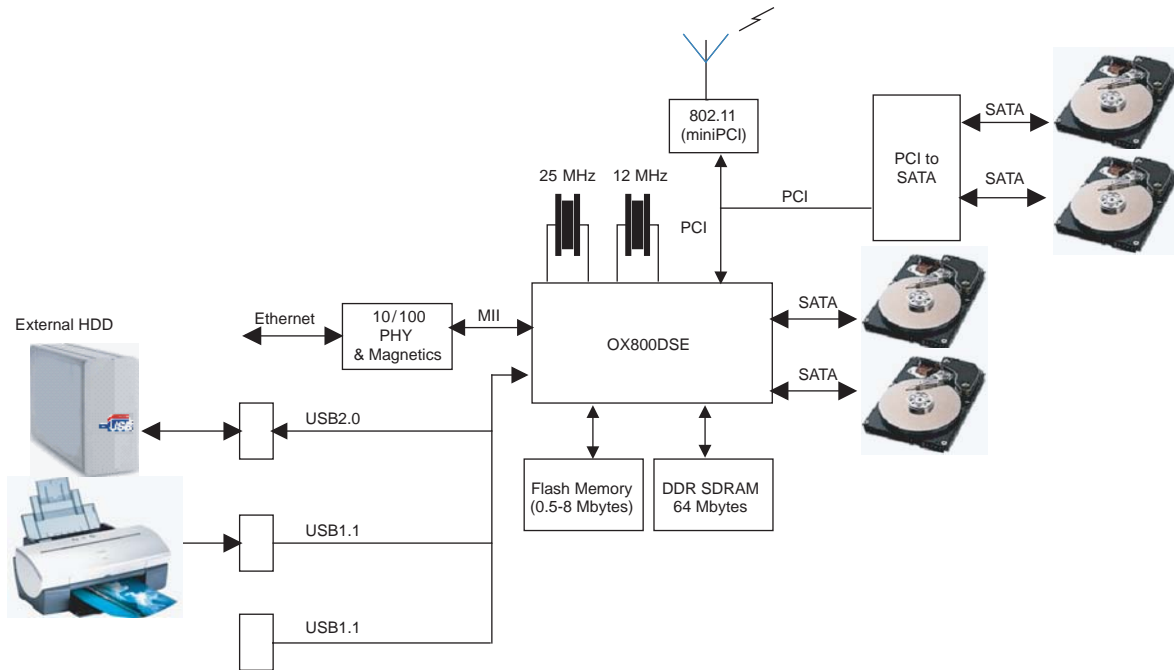


Figure 3 exemplifies a more-capable application in which the capacity of the OXE800DSE has been expanded to support four SATA drives in addition to an Ethernet connection, external HDD and printer.

Figure 3 Sample Four-SATA OXE800DSE Application



Operating Conditions

Tables 1 and 2 detail the required operating conditions for the device.

Table 1 Absolute Maximum Device Ratings

Symbol	Parameter	Rating	Max	Units
V_{DD}	DC supply voltage	1.2 V 3.3 V	1.8 3.8	V
V_{IN}	DC input voltage	2.5-V input buffer 3.3-V input buffer 3.3-V interface/5-V tolerant input buffer	3.6 4.8 6.5	V
V_{OUT}	DC output voltage	2.5-V output buffer 3.3-V output buffer 3.3-V interface/5-V tolerant output buffer	3.6 4.8 6.5	V
T_{STG}	Storage temperature	Storage temperature	-40 to 85	°C

Table 2 Recommended Operating Conditions

Symbol	Parameter	Rating	Min	Max	Units
V_{DD}	DC supply voltage for internal	1.2 V 3.3 V	1.14 3.0	1.26 3.6	V
	DC supply voltage for I/O block	2.5-V I/O	2.3	2.7	
V_{IN}	DC input voltage	2.5-V input buffer 3.3-V input buffer 3.3-V interface/5-V tolerant input buffer	2.3 3.0 3.0	2.7 3.6 5.25	V
V_{OUT}	DC output voltage	2.5-V output buffer 3.3-V output buffer 3.3-V interface/5-V tolerant output buffer	2.3 3.0 3.0	2.7 3.6 3.6	
T_A	Ambient temperature range		0	70	°C

Electrical Characteristics

Table 3 details the required DC electrical characteristics for the device.

Symbol	Parameter	Condition	Min	Type	Max	Units
V_{IH}	Input high voltage	CMOS Interface	2.0			V
V_{IL}	Input low voltage	CMOS Interface			0.8	V
V_T	Switching threshold			1.4		V
V_{T^+}	Schmitt trigger, positive-going threshold	CMOS			2.0	V
V_{T^-}	Schmitt trigger, negative-going threshold	CMOS	0.8			V
I_{IH}	Input high current: Input buffer Input buffer with pull-down	$V_{IN} = V_{DD}$	-10 10	33	10 60	μA
I_{IL}	Input low current: Input buffer Input buffer with pull-up	$V_{IN} = V_{SS}$	-10 -60	-33	10 -10	μA
V_{OH}	Output high voltage	$I_{OH} = -1 \mu A$ $I_{OH} = -1 mA$ to $-24 mA$	$V_{DD} - 0.05$ 2.4			V
V_{OL}	Output low voltage	$I_{OL} = 1 \mu A$ $I_{OL} = 1 mA$ to $24 mA$			0.05 0.4	V
I_{OZ}	Tri-state output leakage current	$V_{OUT} = V_{SS}$ or V_{DD}	-10		10	μA
I_{DD}	Quiescent supply current				100	μA
C_{IN}	Input capacitance	Any input & bidirectional buffers			4	pF
C_{OUT}	Output capacitance	Any output buffer			4	pF

Power Consumption

Table 4 gives typical power consumption figures for the OXE800DSE on a quad test board with the following additional features:

- The VIA PCI SATA chip has been removed
- The 10/100 PHY has been removed
- A PCI Gb PHY is being used

		System Idle After Login		Max Reading/Writing Data to the Disk	
		mA	W	mA	W
1.2 V	Total	377		403	
3.3 V	Total	167		180	
2.5 V	Total	184		329	
Package power			1.4365		1.8803

Pinout & Package Information

The OXE800DSE is supplied as a 272-pin PBGA package.

Figure 4 shows the OXE800DSE pin layout.

Figure 4 OXE800DSE Pin Layout

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18		
A	VSS	GPIO_27	GPIO_29	GPIO_32	MEM_DQ15	MEM_DQ12	MEM_DQS1	MEM_DQ9	MEM_VREF1	MEM_A13	MEM_A11	MEM_A10	MEM_FBCK	MEM_CK	MEM_A4	MEM_A3	MEM_A1	MEM_VREF0		
B	GPIO_24	GPIO_26	GPIO_28	GPIO_31	GPIO_34	MEM_DQ13	MEM_DQ11	MEM_DQ8	MEM_CS_N1	MEM_A12	MEM_A9	MEM_A7	MEM_A5	MEM_CK_N	MEM_A2	MEM_A0	MEM_RAS_N	MEM_DMO		
C	GPIO_21	GPIO_23	GPIO_25	GPIO_30	GPIO_33	MEM_DQ14	MEM_DQ10	MEM_DM1	MEM_CAS_N	MEM_A8	MEM_A6	VSS_MEM	MEM_BA1	MEM_BA0	MEM_WE_N	MEM_CS_N0	MEM_DQ7	MEM_DQ4		
D	GPIO_18	GPIO_19	GPIO_22	VDD33	VSS	VSS_MEM	VSS_MEM	VDD12_MEM	VSS_MEM	MEM_CKE	VDD25_MEM	VDD12_MEM	VSS_MEM	MEM_DQ5	MEM_DQ6	MEM_DQS0	MEM_DQ3	MEM_DQ2		
E	GPIO_13	GPIO_14	GPIO_20	VDD12	VSS_MEM	VDD25_MEM							VDD25_MEM	VSS_MEM	VDD12_MEM	MEM_DQ0	MEM_DQ1	SATA_CLKO		
F	GPIO_6	GPIO_12	GPIO_15	GPIO_17	VDD25_MEM									SATA_VDDOSC	SATA_VSSOSC	SATA_VSS	SATA_VSS	SATA_CLKI		
G	TEST_EN	HIGH_Z_N	GPIO_7	GPIO_16			VSS_MEM	VDD25_MEM	VSS_MEM	VSS_MEM	VSS_MEM	VDD25_MEM			SATA0_REXT	SATA0_VDDTX	SATA0_TXP	SATA0_TXN		
H	USBC_DM	USBC_DP	RESET_N	GPIO_8			VSS	VDD12	VDD25_MEM	VDD25_MEM	SATA_VSSPLL	SATA_VSSPLL			SATA_VSS	SATA1_VDDRX	SATA0_RXN	SATA0_RXP		
J	USBB_DM	USBB_DP	MIL_MDIO	MIL_MDC			USB_VDD12	VSS	VDD33	VSS	SATA_VDDPLL	SATA_VDDPLL			SATA_VSS	SATA0_VDDRX	SATA_VSS	SATA_VSS		
K	USB_VSSA33C	USB_VSS12	USB_VDDA33T1	USB_VDD12			USB_VSS12	USB_VDDA33T1	USB_VSSA33T1	VSS	SATA_VDDPLL	SATA_VDDPLL			SATA_VSS	SATA1_VDDTX	SATA1_RXP	SATA1_RXN		
L	USBA_DP	USBA_DM	USB_VSSA33T1	USB_REXT			VDD12	VSS	VSS	VDD33	SATA_VSSPLL	SATA_VSSPLL			SATA1_REXT	VDD12A_PLLA	SATA1_TXN	SATA1_TXP		
M	USB_VSSA33T1	USB_VDDA33C	USB_VSSX0	MIL_TXEN			VSS	VDD12	VDD33	VSS	VSS	VDD12			PLLA_FILTER	VSSD_PLLA	VBBD_PLLA	SATA_VSS		
N	USB_X1	USB_ANALOG_TEST	MIL_CRIS	MIL_TXD0	NC										PCI_A_D30	PCI_A_D31	VDD12_PCI	VDD12A_PLLA	VSSA_PLLA	
P	CLKO	MIL_COL	MIL_TXD2	NC	MIL_TXER	VDD33									PCI_A_D24	PCI_A_D29	PCI_A_D28	PCI_A_D27	PCI_A_D26	PCI_A_D25
R	MIL_TXD1	MIL_TXD3	NC	MIL_RXDV	NC	GPIO_11	GPIO_4	PCI_A_D12	PCI_A_D14	PCI_A_D17	PCI_PAR	PCI_A_D21	PCI_C_BE_N3	VSS_PCI	VSS	VSS	PCI_A_D23	PCI_A_D22		
T	NC	MIL_RXER	MIL_RXD1	NC	NC	GPIO_5	GPIO_3	PCI_A_D0	VDD12_PCI	VSS_PCI	VDD33	VDD33	VDD33	VDD33	VSS	VSS	PCI_A_D20	PCI_A_D19		
U	NC	MIL_RXD0	NC	GPIO_10	GPIO_9	GPIO_2	GPIO_0	PCI_A_D2	PCI_A_D4	PCI_A_D7	PCI_A_D8	PCI_A_D11	PCI_A_D15	PCI_DEVSEL_N	PCI_FRAME_N	PCI_RDY_N	PCI_A_D16	PCI_A_D18		
V	MIL_TXCLK	MIL_RXD3	MIL_RXCLK	VSS	PCI_CLK	GPIO_1	PCI_A_D1	PCI_A_D3	PCI_A_D5	PCI_A_D6	PCI_C_BE_N0	PCI_A_D9	PCI_A_D10	PCI_A_D13	PCI_C_BE_N1	PCI_STOP_N	PCI_RDY_N	PCI_C_BE_N2		

Table 5 on page 9 details the pin allocations for the device.

<i>Table 5 OXE800DSE Pin Allocations (Sheet 1 of 4)</i>				
Ball	No. Bits	Type ⁽¹⁾	Name	Description
Clocks, Reset & Mode (6 pins)				
P1	1	O	CLKO	25-MHz reference clock out
H4	1	I	RESET_N	Reset input
G2	1	I	HIGH_Z_N	Force all inputs to high impedance
G1	1	I	TEST_EN	Enable test (JTAG)
F18	1	I	SATA_CLKI	25-MHz reference clock input; either crystal oscillator or external clock
E18	1	O	SATA_CLKO	Reference clock output. Crystal oscillator output
Ethernet Interface (18 pins)				
R2,P3,R1,N4	4	O	MII_TXD[3:0]	Transmit data—100 Mbps MII[3:0]—MII @ 25 MHz
V2,R5,T3,U2	4	I	MII_RXD[3:0]	Receive data—100 Mbps MII[3:0]—MII @ 25 MHz
J3	1	B	MII_MDIO	MDIO serial data
J4	1	O	MII_MDC	MDIO clock
N3	1	I	MII_CRS	Carrier sense
P5	1	O	MII_TXER	Transmit error
T2	1	I	MII_RXER	Receive error
V1	1	I	MII_TXCLK	MII transmit clock in—25 MHz
V3	1	I	MII_RXCLK	MII receive clock—25 MHz
M4	1	O	MII_TXEN	Transmit enable
R4	1	I	MII_RXDV	Receive data valid
P2	1	I	MII_COL	Collision detect
SDRAM (47 pins)				
A14	1	2V5_O	MEM_CK	Differential clock (non-inverted)
B14	1	2V5_O	MEM_CK_N	Differential clock (inverted)
A13	1	2V5_I	MEM_FBCK	Feedback clock
D10	1	2V5_O	MEM_CKE	Clock enable
B9,C16	2	2V5_O	MEM_CS_N[1:0]	Chip selects
B17	1	2V5_O	MEM_RAS_N	Read address strobe
C9	1	2V5_O	MEM_CAS_N	Column address strobe
C15	1	2V5_O	MEM_WE_N	Write enable
C13,C14	2	2V5_O	MEM_BA[1:0]	Bank address
A10,B10,A11,A12,B11,C10,B12, C11,B13,A15,A16,B15, A17,B16	14	2V5_O	MEM_A[13:0]	Address
A7,B7,D8,B8,D9,B9,A9,A10, D17,C20,D19,E17,E19,E20, F17,F19	16	2V5_B	MEM_DQ[15:0]	Data input/output
A7,D16	2	2V5_B	MEM_DQS[1:0]	Data in/out strobes
C8,B18	2	2V5_O	MEM_DM[1:0]	Data mask

Table 5 OXE800DSE Pin Allocations (Sheet 2 of 4)				
Ball	No. Bits	Type⁽¹⁾	Name	Description
A9,A18	2	A	MEM_VREF[1:0]	Voltage references (1.25 V) for SSTL-2
PCI (43 pins)				
N15,N14,P14,P15,P16,P17, P18,P13,R17,R18,R13,T17,T18, U18,R11,U17,U13,R10,V14,R9, U12,V13,V12,U11,U10,V10,V9, U9,V8,U8,V7,T8	32	B	PCI_AD[31:0]	PCI address & data. PCI_AD[15:0]—PCI address & data (lower 16 bits) also serves as STATIC_A[15:0] lower 16 bits of static memory address. PCI_AD[31:16]—PCI address & data (upper 16 bits) also serves as STATIC_D[15:0] static memory controller bus
U14	1	B	PCI_DEVSEL_N	PCI device selection
U16	1	B	PCI_IRDY_N	PCI initiator ready
V17	1	B	PCI_TRDY_N	PCI target ready
R14,V18,V15,V11	4	B	PCI_C_BE_N[3:0]	PCI command/byte enable
V5	1	I	PCI_CLK	PCI clock
V16	1	B	PCI_STOP_N	PCI stop
U15	1	B	PCI_FRAME_N	PCI frame
R12	1	B	PCI_PAR	PCI parity
G3,F1,T6,R8	4	I	PCI_REQ[3:0]	PCI host arbiter bus requests. Shared with GPIO
T7, U6,V6,U7	4	O	PCI_GNT[3:0]	PCI host arbiter bus grants. Shared with GPIO
R7, U4,U5,H4	4	O	PCI_CKO	Programmable PCI output clocks. Shared with GPIO
Static memory interface				
N15,N14,P14,P15,P16,P17, P18,P13,R17,R18,R13,T17,T18, U18,R11,U17	16	B	STATIC_D[15:0]	Static memory controller data bus. Shared with PCI
U13,R10,V14,R9,U12,V13,V12, U11,U10,V10,V9,U9,V8,U8,V7, T8	16	O	STATIC_A[15:0]	Lower 16 bits of static memory controller address. Shared with PCI
D1,F4,C4,F3,E2,E1	6	O	STATIC_A[21:16]	Upper 16 bits of static memory controller address. Shared with GPIO
E3,D2	2	O	STATIC_CS_N[1:0]	Shared with GPIO
D3,C1	2	O	STATIC_WE_N[1:0]	Shared with GPIO
F2	1	O	STATIC_OE_N	Shared with GPIO
SATA 0 (5 pins)				
H18	1	I	SATA0_RXP	Receive differential data (+); differential inputs to the PHY. Terminals receive NRZ data at 1.5 or 3.0 Gbps
H17	1	I	SATA0_RXN	Receive differential data (-); differential inputs to the PHY. Terminals receive NRZ data at 1.5 or 3.0 Gbps
G18	1	O	SATA0_TXN	Transmit differential data (-); differential outputs to the PHY. Terminals transmit NRZ data at 1.5 or 3.0 Gbps
G17	1	O	SATA0_TXP	Transmit differential data (+); differential outputs to the PHY. Terminals transmit NRZ data at 1.5 or 3.0 Gbps

<i>Table 5 OXE800DSE Pin Allocations (Sheet 3 of 4)</i>				
Ball	No. Bits	Type ⁽¹⁾	Name	Description
G15	1	A	SATA0_REXT	External 1-K \pm 1% Ω reference resistor
SATA 1 (5 pins)				
K17	1	I	SATA1_RXP	Receive differential data (+); differential inputs to the PHY. Terminals receive NRZ data at 1.5 or 3.0 Gbps
K18	1	I	SATA1_RXN	Receive differential data (-); differential inputs to the PHY. Terminals receive NRZ data at 1.5 or 3.0 Gbps
L17	1	O	SATA1_TXN	Transmit differential data (-); differential outputs to the PHY. Terminals transmit NRZ data at 1.5 or 3.0 Gbps
L18	1	O	SATA1_TXP	Transmit differential data (+); differential outputs to the PHY. Terminals transmit NRZ data at 1.5 or 3.0 Gbps
L15	1	A	SATA1_REXT	External 1-K \pm 1% Ω reference resistor
USB2.0 Port A (6 pins)				
N2	1	A	USB_ANALOG_TEST	
N1	1	I	USB_XI	12-MHz crystal oscillator XI signal
M3	1	O	USB_XO	Crystal oscillator XO signal
L2	1	B	USBA_DM	Differential data minus—480 Mbps
L1	1	B	USBA_DP	Differential data plus—480 Mbps
L4	1	A	USB_REXT	External 3.6-K \pm 1% Ω reference resistor
USB1.1 Port B (2 pins)				
J1	1	B	USBB_DM	Differential data minus—12 Mbps
J2	1	B	USBB_DP	Differential data plus—12 Mbps
USB1.1 Port C (2 pins)				
H1	1	B	USBC_DM	Differential data minus—12 Mbps
H2	1	B	USBC_DP	Differential data plus—12 Mbps
MISC (1 pin)				
M15	1	A	PLLA_FILT	System PLL filter
GPIO (35 pins)				
B5,C5,A4,B4,C4,A3,B3,A2,B2,C3,B1,C2,D3,C1,E3,D2,D1,F4,G4,F3,E2,E1,F2,R7,U4,U5,H4,G3,F1,T6,R8,T7,U6,V6,U7	35	B	GPIO[34:0] ⁽²⁾	General purpose I/O pins. Uses depend on pin multiplexing, including PCI, UART, audio, PWM & static signals
Power & Ground (91 pins)				
N17	1	P	VDD12A_PLLA	System PLL analog 1.2-V supply
L16	1	P	VDD12D_PLLA	System PLL digital 1.2-V supply
M16	1	P	VSSD_PLLA	System PLL ground
N18	1	P	VSSA_PLLA	System PLL ground
M17	1	P	VBBD_PLLA	System PLL bulk bias (0 V)
K16	1	P	SATA1_VDDTX0	SATA Tx power (1.2 V)

Table 5 OXE800DSE Pin Allocations (Sheet 4 of 4)

Ball	No. Bits	Type ⁽¹⁾	Name	Description
G16	1	P	SATA0_VDDTX0	SATA Tx power (1.2 V)
H16	1	P	SATA1_VDDRX0	SATA Rx power (1.2 V)
J16	1	P	SATA0_VDDRX1	SATA Rx power (1.2 V)
L11,L12,H11,H12	4	P	SATA_VSSPLL	SATA PLL ground
K12,K11,J11,J12	4	P	SATA_VDDPLL	PLL supply (1.2 V)
F15	1	P	SATA_VSSOSC	SATA ground for the crystal oscillator
F14	1	P	SATA_VDDOSC	SATA 3.3-V power supply for the crystal oscillator
F16,F17,H15,J15,J17,J18,K15,M18	8	P	SATA_VSS	Ground
M2	1	P	USB_VDDA33C	Analog 3.3-V supply
K1	1	P	USB_VSSA33C	Analog ground
K4,J7	2	P	USB_VDD12	Digital 1.2-V supply
K7,K2	2	P	USB_VSS12	Digital ground
M1,L3,K9	3	P	USB_VSSA33T1	Analog ground
R3,U3	2	P	USB_VDDA33T1	Analog 3.3-V supply
A1,R16,T15,T16,D5,J8,M7,M10,K10,H7,L8,L9,M11,J10,V4	15	P	VSS	Ground
E4,L7,M8,M12,H8	5	P	VDD12	1.2-V supply
D4,J9,P6,M9,L10,T11,T12,T13,T14	9	P	VDD33	3.3-V supply
E13,G12,D11,H10,H9,G8,E6,F5	8	P	VDD25_MEM	2.5-V SDRAM interface supply
E14,C12,D7,D13,G11,D9,G10,G9,G7,D6,E5	11	P	VSS_MEM	SDRAM interface ground
E15,D12,D8	3	P	VDD12_MEM	1.2-V SDRAM interface supply
N16,T9	2	P	VDD12_PCI	1.2-V PCI bus interface supply
R15,T10	2	P	VSS_PCI	PCI ground
NC (9 pins)				
N5,P4,R3,T1,T5,U3,T4,R6,U1	9			Do not connect

Notes:

1 Type key: format is [(W_X)] where the following conventions apply:

W—Supply		X—Type	
5V	5-V tolerant 3.3 V	I	Input
3V3	3.3 V	O	Output
2V5	2.5	B	Bidirectional
		A	Analog

2 Any of the 35 GPIO pins on the device can be assigned to a primary function, a secondary function or bit-programmable general-purpose I/O in response to peripheral control register tertiary settings. JTAG must not be enabled in conjunction with HIGH_Z_N asserted low.

Figures 5 and 6 show the OXE800DSE package.

Figure 5 OXE800DSE Package—Top & Side View

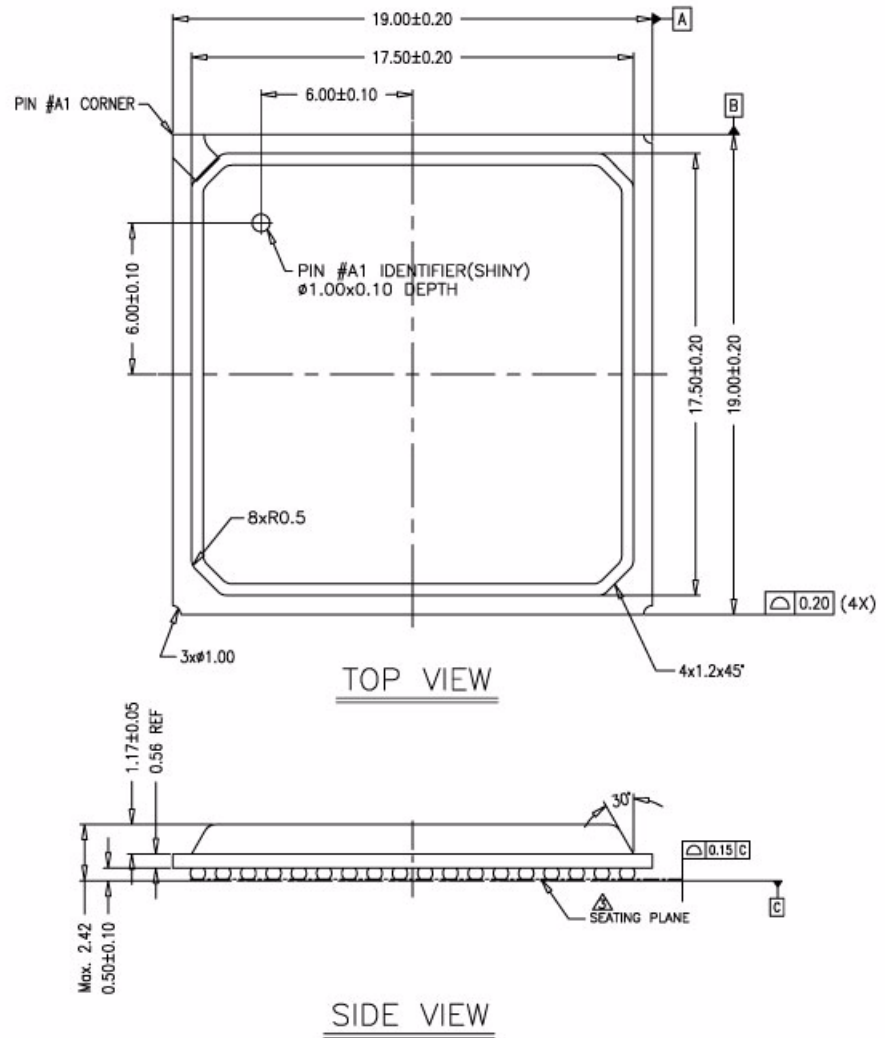
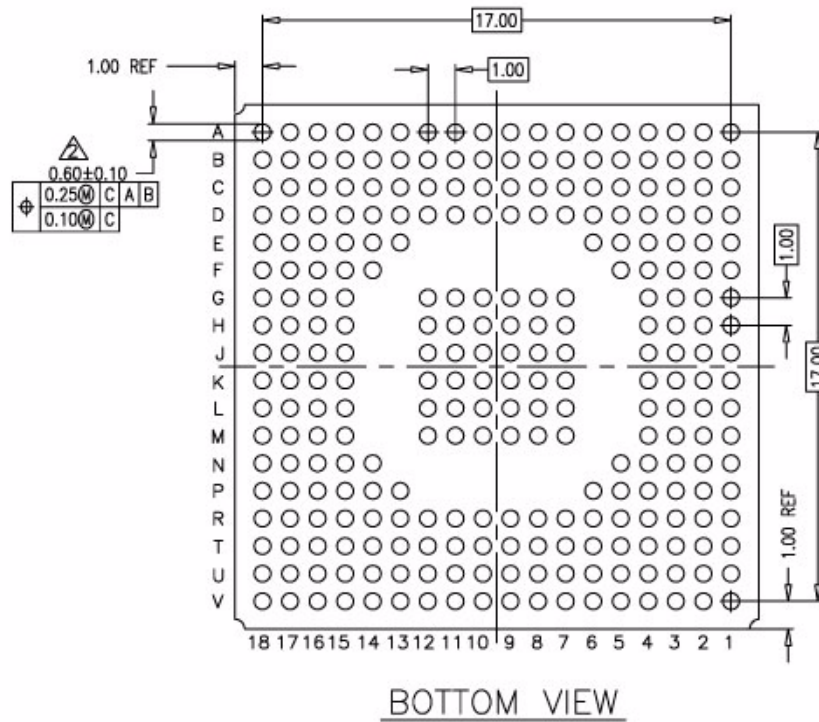


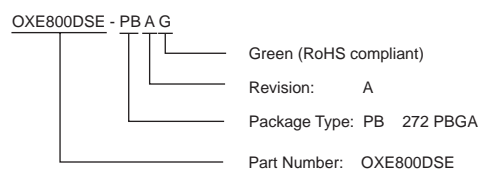
Figure 6 OXE800DSE Package—Bottom View



Ordering Information

The order code for the Oxford Semiconductor OXE800DSE is OXE800DSE-PBAG.

The following conventions are used to identify Oxford Semiconductor products:



Revision Information

Table 6 documents the revisions of this guide.

Revision	Modification
Sep 06	First publication
Mar 07	Package information corrected; device characteristics & operating conditions added; document category changed to External—Free Release
Jul 07	Feature revision
Oct 07	Feature revision

Application Notes

The following application notes apply to the OXE800DSE:

TBD

Contacting Oxford Semi- conductor

See the Oxford Semiconductor website (<http://www.oxsemi.com>) for further details about Oxford Semiconductor devices, or email sales@oxsemi.com.

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